

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	247	(@ad<"20000216") and 257/777. ccls. and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 18:44
L2	152	L1 and ((chip or die) with wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 18:39
L3	1	("6103552").PN.	USPAT; USOCR	OR	OFF	2006/09/16 18:38
L4	149	L1 and (encapsulation or encapsulant or epoxy or cur\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 18:45
L5	120	(@ad<"20000216") and 257/e21. 526.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 18:48
L6	158	L1 and (encapsulation or encapsulant or epoxy or cur\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 18:46
L7	9	L6 not L4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 18:45
L8	52	L5 and (encapsulation or encapsulant or epoxy or cur\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 18:48

## EAST Search History

L9	19	(@ad<"20000216") and 257/e23.085.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 18:47
L10	818	(@ad<"20000216") and 438/598,67,107,110,406,455.ccls. and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 19:12
L11	357	L10 and (encapsulation or encapsulant or epoxy or cur\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 18:51
L12	225	L11 and (cut or cutting or singulation or singulat\$3 or dice or saw or sawing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 18:51
L13	281	L11 and (hole or recess or via or groove or trench or opening)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 18:50
L14	179	L13 and (cut or cutting or singulation or singulat\$3 or dice or saw or sawing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 18:51
L15	179	L14 and (insulat\$3 or dielectric or encapsulation or encapsulant or epoxy or cur\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 18:52
L16	87	L14 and (solfer or ball\$1 or bump\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 18:52

## EAST Search History

L17	106	L14 and (solder or ball\$1 or bump\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 18:52
L18	4	("4600600"   "5620927"   "5849608"   "5851845").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/16 18:58
L19	73	L14 not L17	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/16 18:58
L20	1783	(@ad<"20000216") and (wafer with ((encapulant or encapsulat\$3 or epoxy or adhesive or liquid or thermoplastic or (pressure adj sensitive)) and (scale or level)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 19:17
L21	1955	(@ad<"20000216") and (wafer with ((encapulant or encapsulat\$3 or epoxy or adhesive or adhesion or liquid or thermoplastic or (pressure adj sensitive)) and (scale or level)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 19:36
L22	560	L21 and ((encapulant or encapsulat\$3 or epoxy or adhesive or adhesion or liquid or thermoplastic or (pressure adj sensitive)) with (hole or opening or recess or via or trench or solder or colum or cylinder or cylindrical or bump))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 19:16
L23	237	L22 and (wafer near (scale or level))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 19:17
L24	234	L23 not L19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 19:28
L25	1	("6495916").PN.	USPAT; USOCR	OR	OFF	2006/09/16 19:28

## EAST Search History

L26	1961	(@ad<"20000216") and (wafer with ((underfill or encapsulant or encapsulat\$3 or epoxy or adhesive or adhesion or liquid or thermoplastic or (pressure adj sensitive)) and (scale or level)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 19:55
L27	6	L26 not L21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 19:37
L28	2054	(@ad<"20000216") and (wafer with ((elastomer or compliant or silicone or underfill or encapsulant or encapsulat\$3 or epoxy or adhesive or adhesion or liquid or thermoplastic or (pressure adj sensitive)) and (scale or level)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 20:03
L29	20	L28 and 257/778.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 20:06
L30	1	("20040113246").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/16 20:03
L31	25	L28 and 438/108.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 20:06
L32	19	L31 not L29	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/16 20:06
L33	3	("5128746"   "5493075"   "6046071").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/16 20:08
L34	17	("6228681").URPN.	USPAT	OR	OFF	2006/09/16 20:08